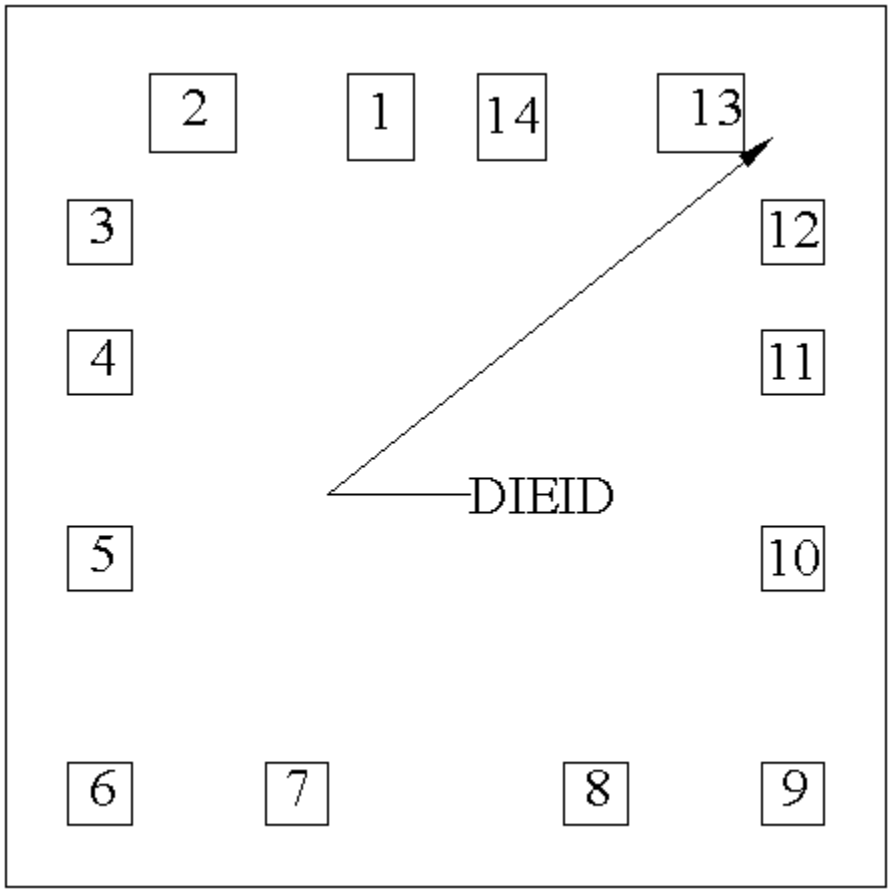
LM139 MDS MCD2070A
LOW POWER LOW OFFSET VOLTAGE QUAD COMPARATOR

April 14,2005

DIE LAYOUT (F-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	1901F	Bond Pad Opening Size (min)	86μm x 86μm
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Bare Back
Die Size (Drawn)	1194μm x 1194μm 47.0mils x 47.0mils	Back Side Connection	Floating
Thickness	330μm Nominal		
Min Pitch	179μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (F -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Output 2	1	-89	447	91	x	117
Output 1	2	-345	452	117	x	107
V+	3	-470	292	86	x	86
-Input 1	4	-470	114	86	x	86
+Input 1	5	-470	-152	86	x	86
-Input 2	6	-470	-470	86	x	86
+Input 2	7	-203	-470	86	x	86
-Input 3	8	203	-470	86	x	86
+Input 3	9	470	-470	86	x	86
-Input 4	10	470	-152	86	x	86
+Input 4	11	470	114	86	x	86
GND	12	470	292	86	x	86
Output 4	13	345	452	117	x	107
Output 3	14	89	447	91	x	117

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